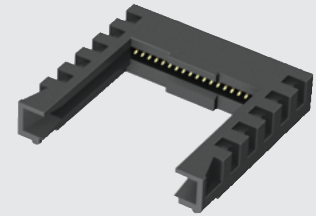


MB1-130-01-F-S-01-SL-N



(1,00 mm) .0394"

MB1 SERIES

MINI EDGE CARD SOCKET WITH GUIDES

Mates with:
(0,80 mm) .031" PCB,
(1,60 mm) .062" PCB

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material: Black LCP
Contact Material: BeCu
Plating: Sn or Au over 50µ" (1,27 µm) Ni
Current Rating: 2.2 A per pin (6 pins powered)
Operating Temp Range: -55°C to +125°C
Insertion Depth: (5,26 mm) .207" to (6,10 mm) .240"
RoHS Compliant: Yes

Processing:
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (20-30) (0,15 mm) .006" max (40-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note: Patented

Important Note: Samtec recommends that pads on the mating board be Gold plated.

Note: Some sizes, styles and options are non-standard, non-returnable.

MB1

1

NO. OF PINS

01

PLATING OPTION

S

CARD SLOT

SL

OTHER OPTION

20, 30, 40, 50

-F

= Gold flash on contact, Matte Tin on tail

-L

= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

Specify CARD SLOT from chart

CARD SLOT	A	MATES WITH BOARD THICKNESS
-01	(0,97) .038	(0,80) .031
-02	(1,83) .072	(1,60) .062

-N OPTION

ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.

OTHER SOLUTIONS

Flex Card System

- .050" (1,27 mm) (FCF/EMF Series) systems
- Vertical and horizontal
- Header with snap-on card guides for design flexibility
- Elevated design now available
- PCMCIA (PCMT/PCMS Series) Compact Flash (CFT/CFS Series) compatible applications available
- Ideal for multiple add-on cards
- Solder locks for mechanical stability
- Any size from 40 to 100 contacts

